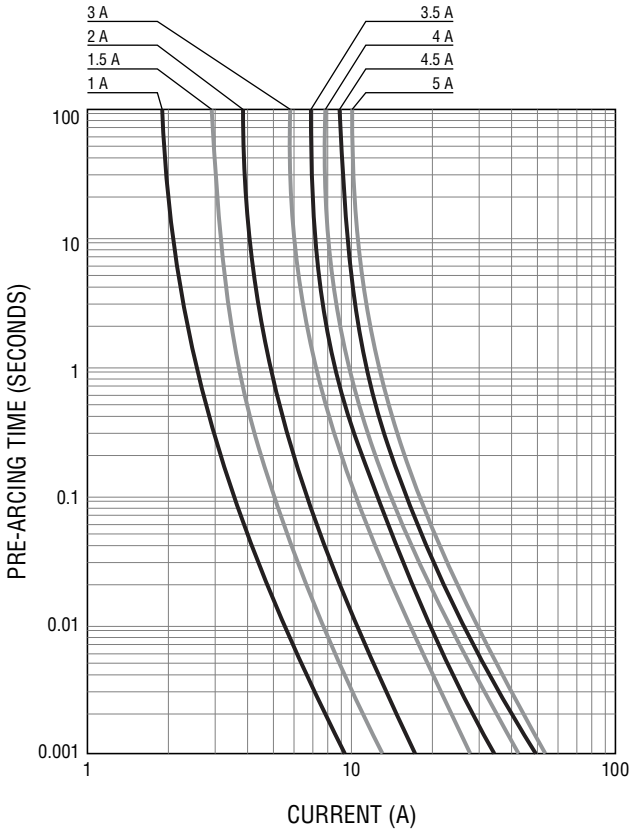
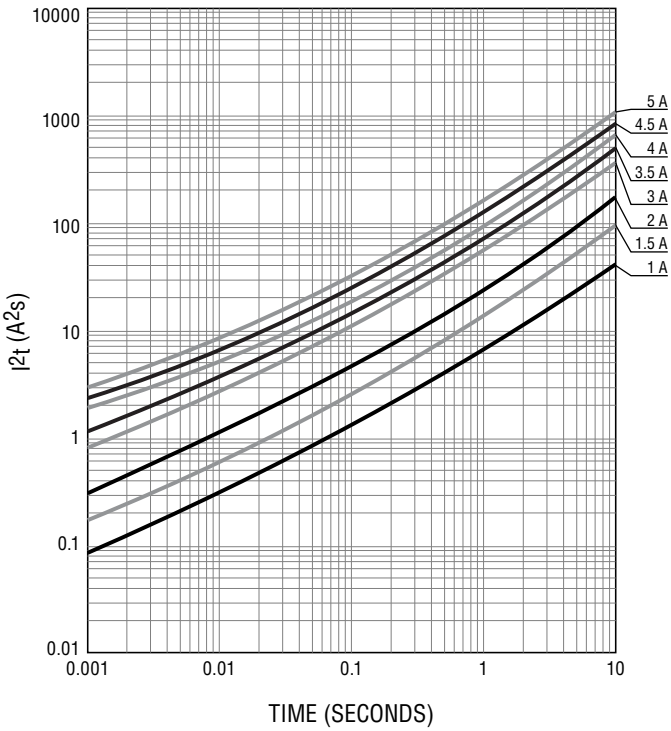
Average Pre-Arcing Time vs. Current Curves



Average I²t vs. t Curves



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Users should verify actual device performance in their specific applications.
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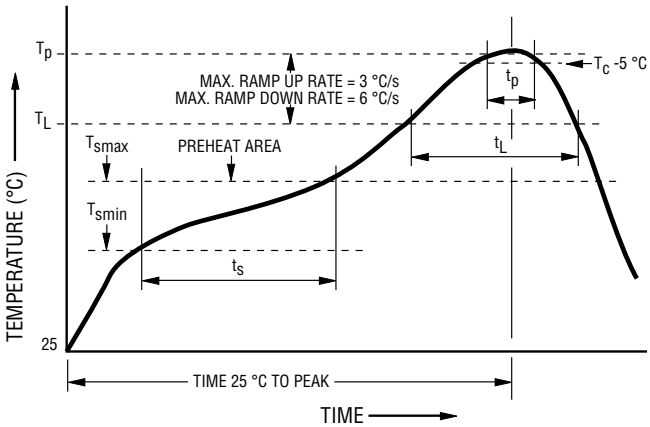
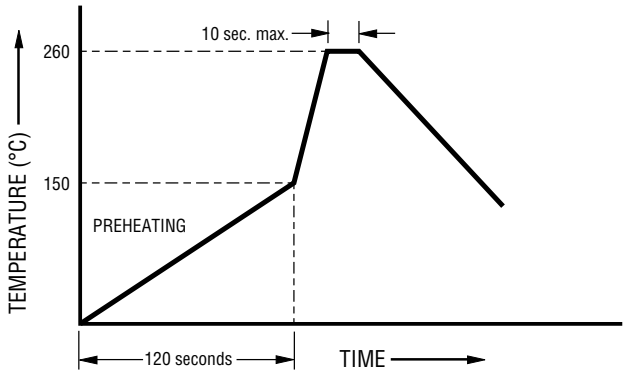
Solder Reflow Recommendations



Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. (T_{smin}) Temperature Max. (T_{smax}) Time (t_s) from (T_{smin} to T_{smax})	 150 °C 200 °C 60~120 seconds
Ramp Up Rate (T_L to T_p)	3 °C / second max.
Liquidous Temperature (T_L) Time (t_L) maintained above T_L	217 °C 60~150 seconds
Peak Package Body Temperature (T_p)	260 °C
Time (t_p)* within 5 °C of the specified classification temperature (T_c)	30 seconds*
Ramp Down Rate (T_p to T_L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

* Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

Solder Wave Recommendations



Reliability Tests

Test Items	Reference Standard
Visual Inspection	MIL-STD-883 Method 2009
High Temperature Storage	MIL-STD-202 Method 108
Low Temperature Storage	IEC 60068-2-1
Temperature Cycling	JESD22 Method JA-104
Biased Humidity	MIL-STD-202 Method 103
High Temperature Operating Life	MIL-STD-202 Method 108
Physical Dimension	JESD22 Method JB-100
Mechanical Vibration	MIL-STD-202 Method 204
Mechanical Shock	MIL-STD-202 Method 213
Resistance to Soldering Heat	MIL-STD-202 Method 210
Salt Spray	MIL-STD-202 Method 101
Solderability	MIL-STD-202 Method 208
Terminal Strength	AEC-Q200-006
Board Flex	AEC-Q200-005
Pull Test	MIL-STD-202 Method 211
Electrical Characterization	Bourns Specification

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